

Title (en)  
HEAT TRANSFER ARRANGEMENT AND ELECTRONIC HOUSING COMPRISING A HEAT TRANSFER ARRANGEMENT AND METHOD OF CONTROLLING HEAT TRANSFER

Title (de)  
WÄRMEÜBERTRAGUNGSANORDNUNG UND ELEKTRONISCHES GEHÄUSE MIT EINER WÄRMEÜBERTRAGUNGSANORDNUNG UND VERFAHREN ZUR STEUERUNG VON WÄRMEÜBERTRAGUNG

Title (fr)  
AGENCEMENT DE TRANSFERT DE CHALEUR ET BOÎTIER ÉLECTRONIQUE COMPRENANT UN AGENCEMENT DE TRANSFERT DE CHALEUR ET PROCÉDÉ DE COMMANDE DE TRANSFERT DE CHALEUR

Publication  
**EP 2377379 A1 20111019 (EN)**

Application  
**EP 09788464 A 20090115**

Priority  
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Abstract (en)  
[origin: WO2010082875A1] A heat transfer arrangement comprises a refrigerant circuit (102). The refrigerant circuit (102) comprises an evaporator (104) adapted to be arranged inside an electronic component housing (202), a condenser (108) adapted to be arranged outside the electronic component housing (202), a first conduit leading (106) from the evaporator (104) to the condenser (108), and a second conduit leading from the condenser (108) to the evaporator (104). A refrigerant is present in the refrigerant circuit (102) and in use, under first temperature conditions, is arranged to self-circulate in the refrigerant circuit (102) by evaporating in the evaporator (104), rising as a gas through the first conduit, condensing in the condenser (108) and flowing through the second conduit to the evaporator (104). In the refrigerant circuit (102) a further separate gas or separate gas mixture is present in a quantity such that in use, under second temperature conditions, said quantity of further separate gas or separate gas mixture expands inside the condenser (108) to thereby displace refrigerant from the condenser (108). Heat transfer is thus controlled. Also an electronic component housing comprising such a heat transfer arrangement and a method of controlling heat transfer from such an electronic housing are provided.

IPC 8 full level  
**H05K 7/20** (2006.01)

CPC (source: EP US)  
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See references of WO 2010082875A1

Citation (examination)  

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